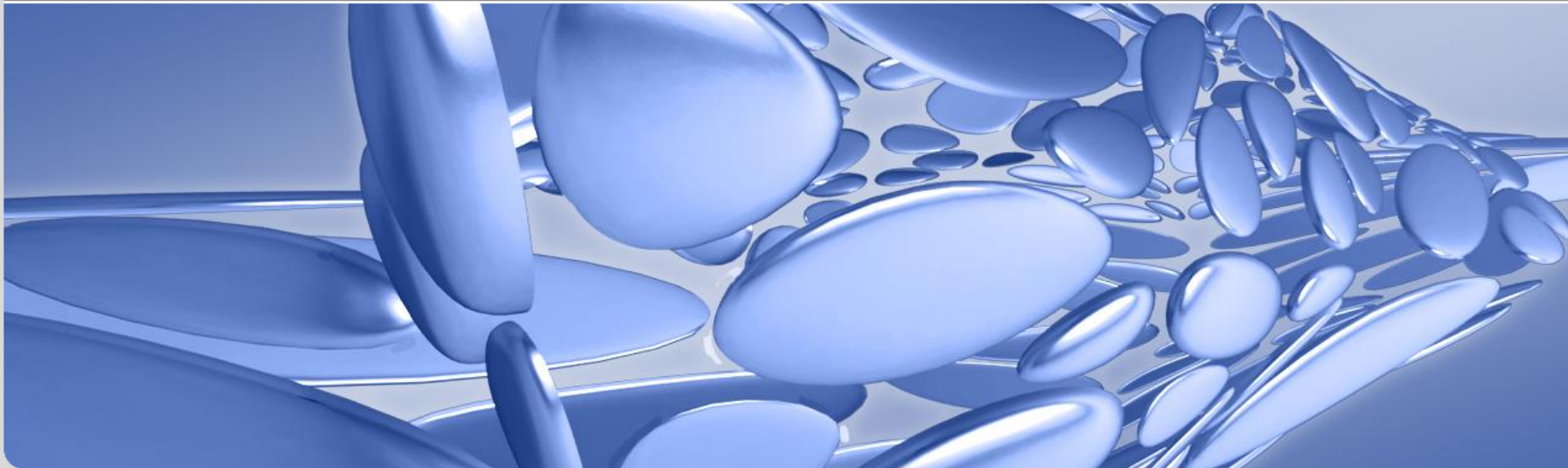
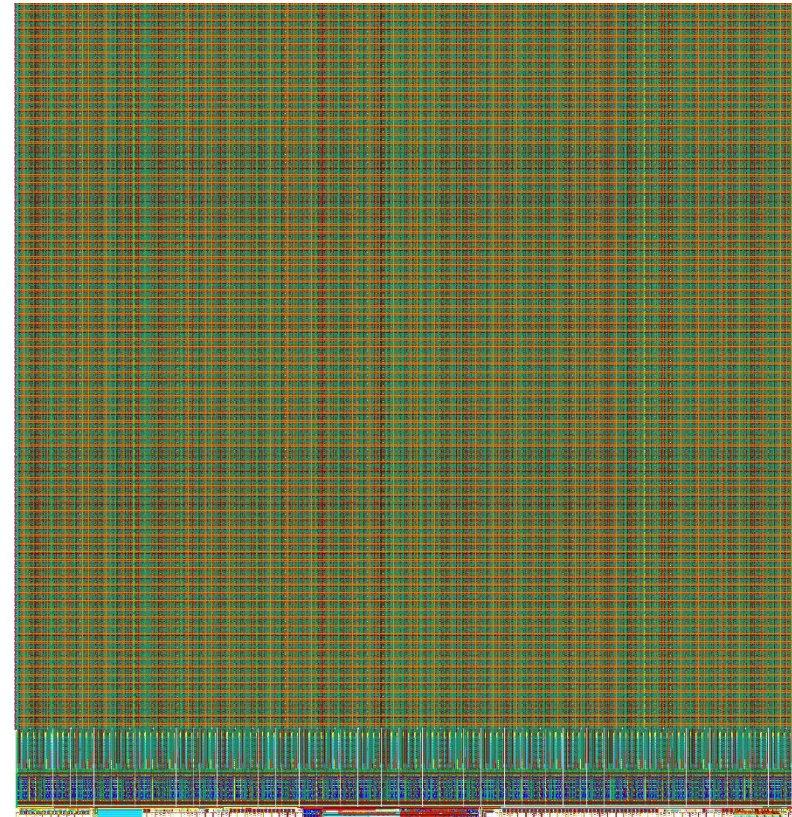


# Two reticle size monolithic pixel detectors ATLASPIX3 and MuPix10

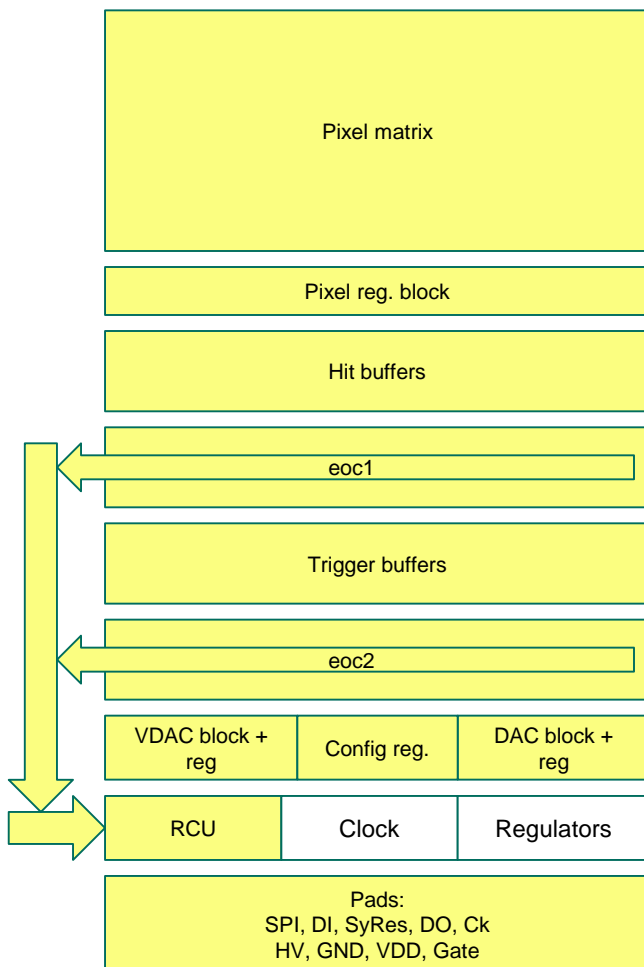
**Ivan Peric**



- ATALSPIX3
- HVCMOS sensor
- The chip has been implemented in 180nm HVCMOS technology of TSI. 200Ωcm wafers have been used.
- Received in September 2019
- Triggered and triggerless readout possible via two concurrent readout structures
- Several configuration methods for different wire count constraints (serial, SPI, single line)
- Data interface similar as RD53
- **Triggered readout can be used as continuous readout with hit sorting**
- Interface:
  - Input CMD line (used for clock generation, L1 triggering with trigger tag, configuring and readback of configuration), like RD53
  - Supports serial powering
  - Size: 20.2mm x 21mm
  - Radiation hard design with SEU tolerant memory



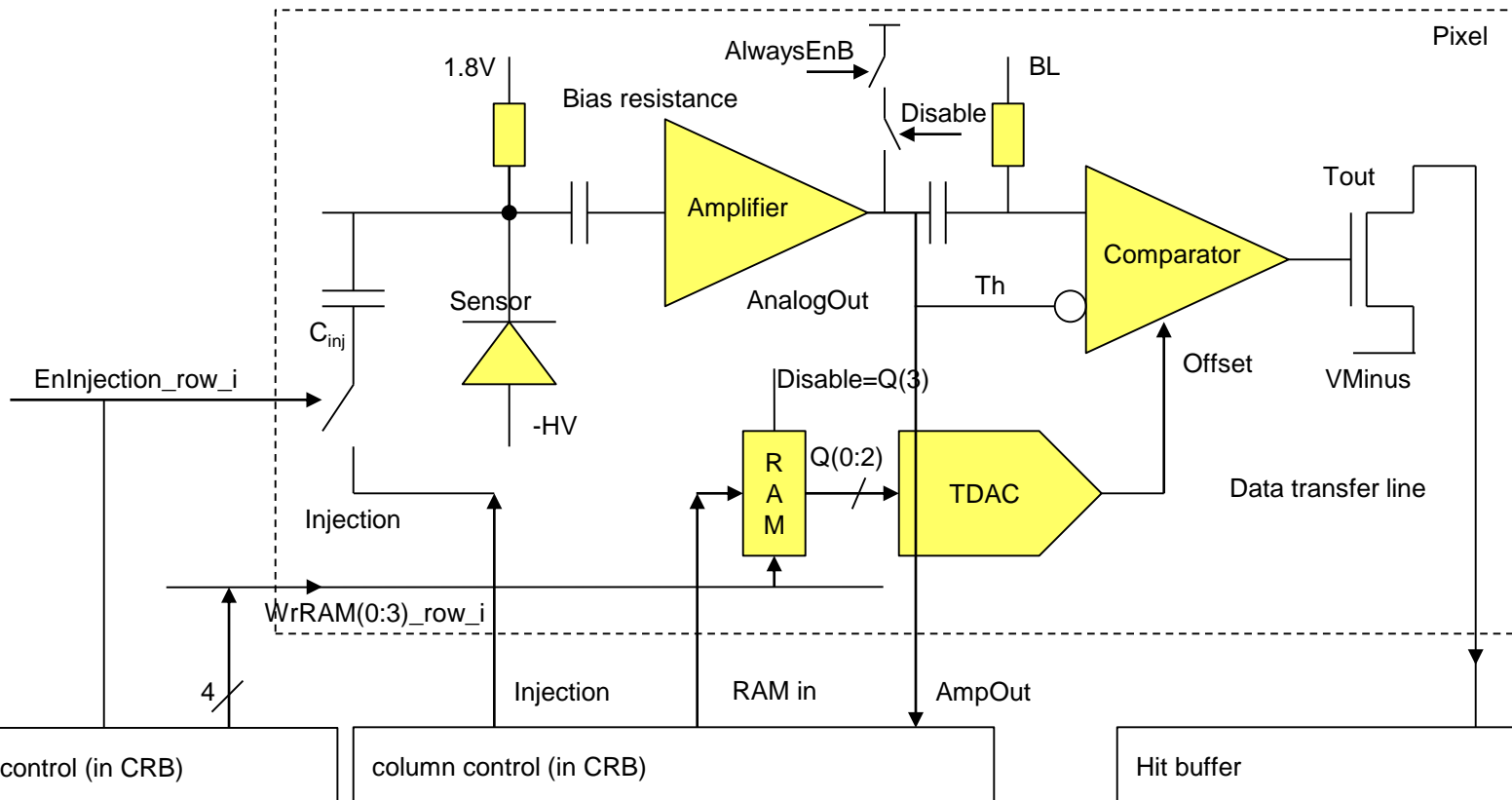
- ATLASPIX3 has a pixel matrix with 132 columns and 372 rows. Pixel size is  $x = 150\mu\text{m}$ ,  $y = 50\mu\text{m}$ . The chip size is  $x = 20.2\text{mm}$ ,  $y = 21\text{mm}$ .
- One column contains 372 pixels, a configuration register block, 372 hit buffers, 80 trigger buffers and two end of column (EoC) blocks. EoC1 is attached to hit buffers and EoC2 to trigger buffers.

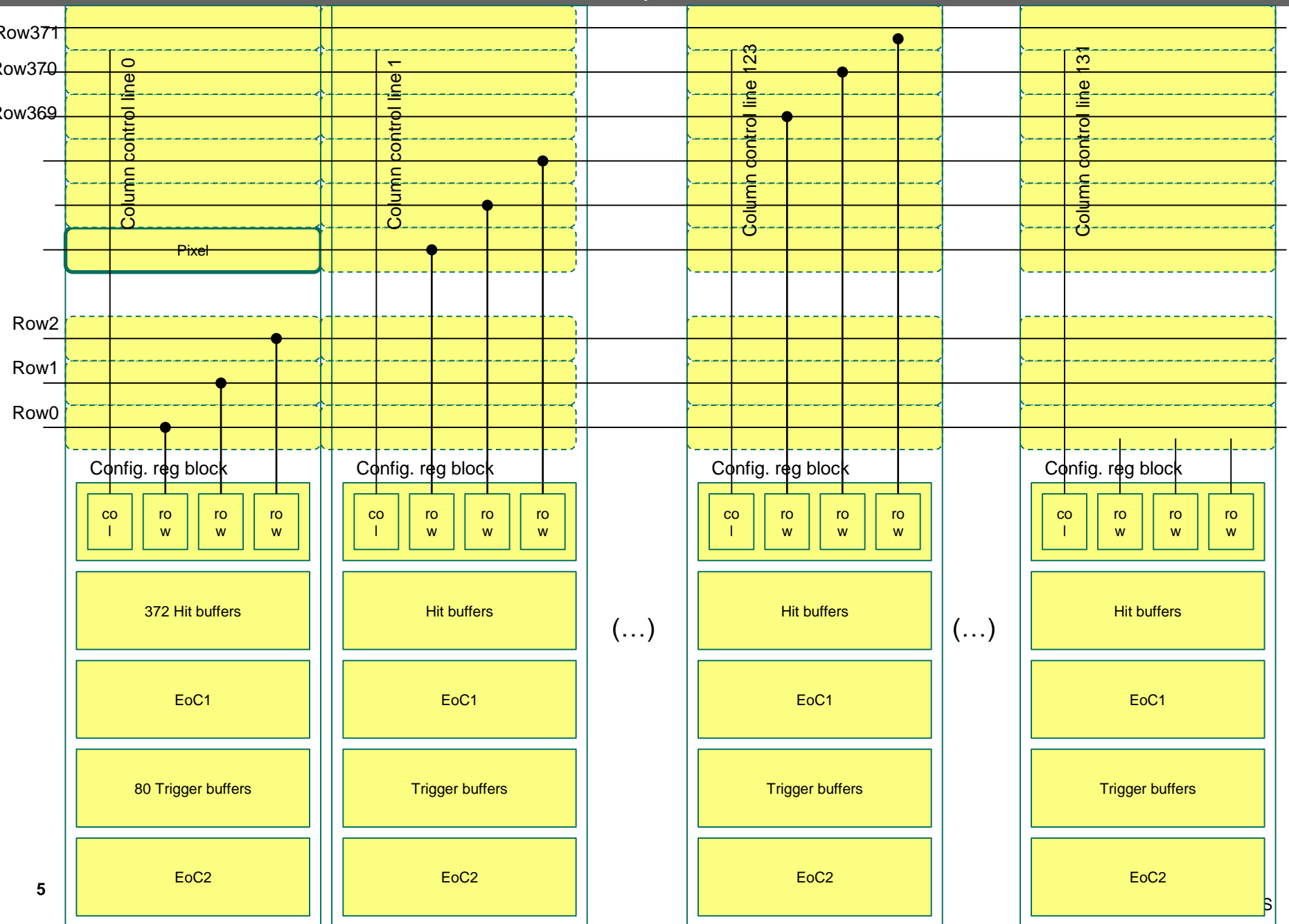


Pixel size (x, y):  $150\mu\text{m} \times 50\mu\text{m}$   
 Matrix size: 132 x 372

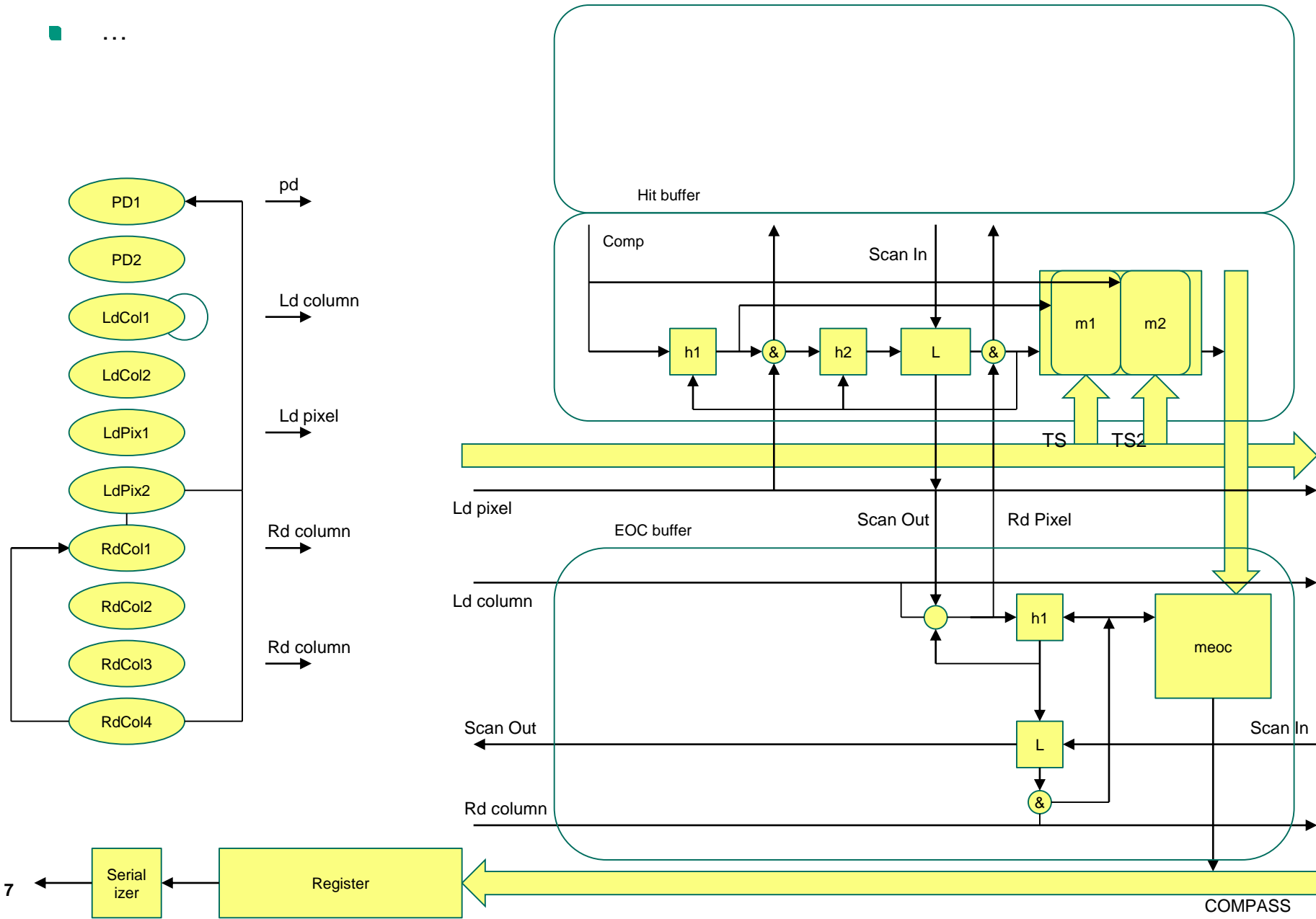
Time stamp: 10 bits, ToT time stamp: 7 bits  
 Programmable TS. frequency: up 160MHz (untriggered), 40MHz (triggered)  
 Output:  
 Triggered: Aurora 66/64 (Max rate 40MHits/s)  
 Untriggered: 8b10b (Max rate 20MHits/s)

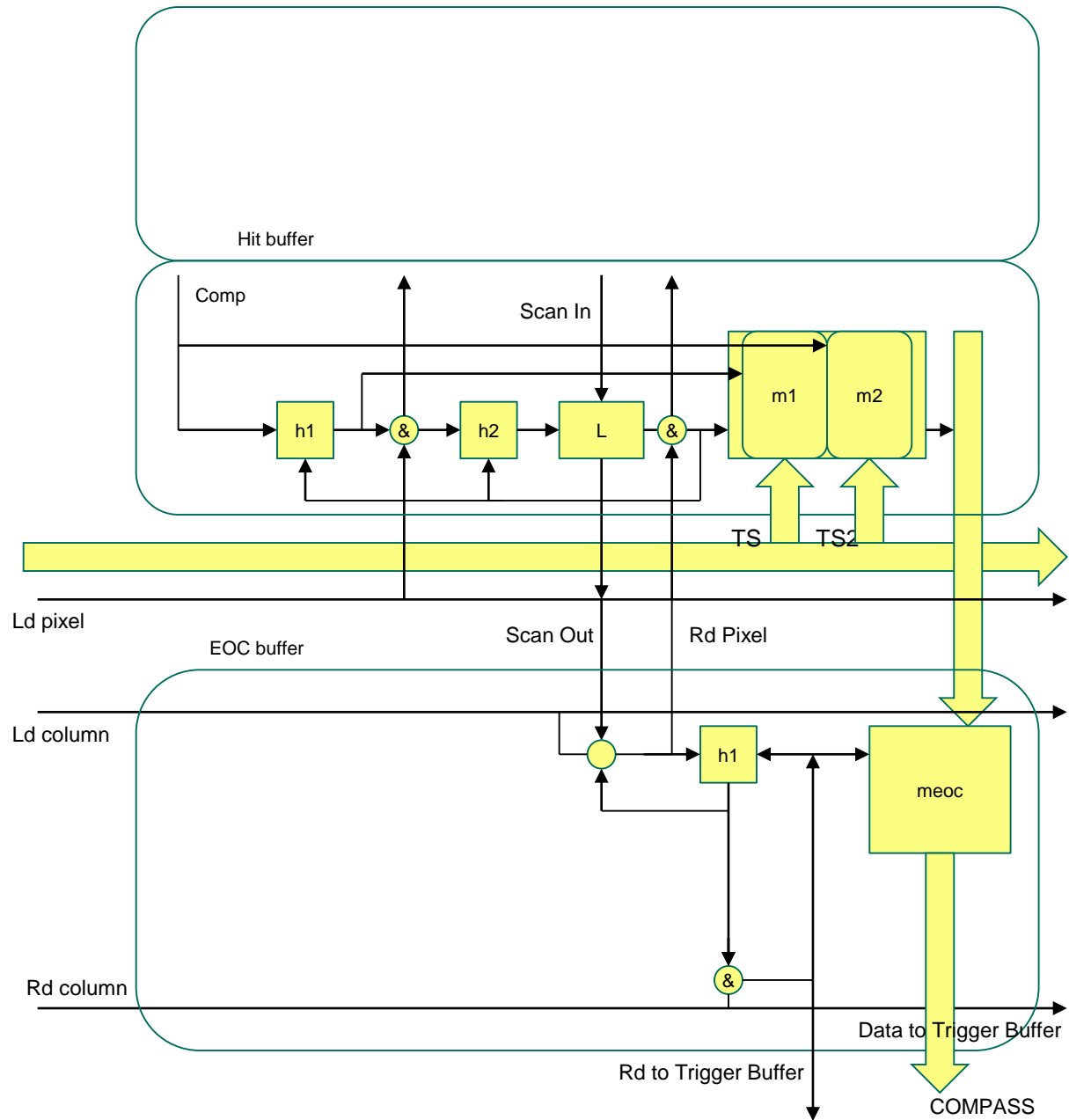
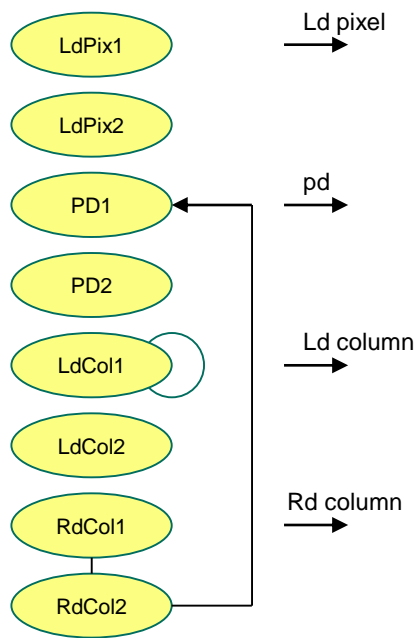
- The pixel contains a deep n-well and the electronics that is inside the n-well. N-well to p-substrate diode is used as sensor.
- Pixel contains sensor diode, charge sensitive amplifier, comparator, threshold tune DAC, RAM for tune bits (3) and disable bit and output driver
- The outputs of the pixels are transmitted to the column periphery (long metal lines)





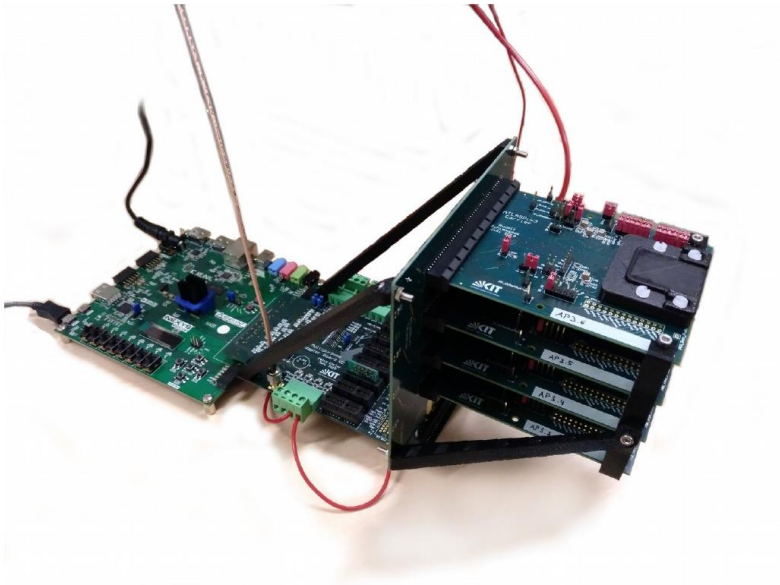
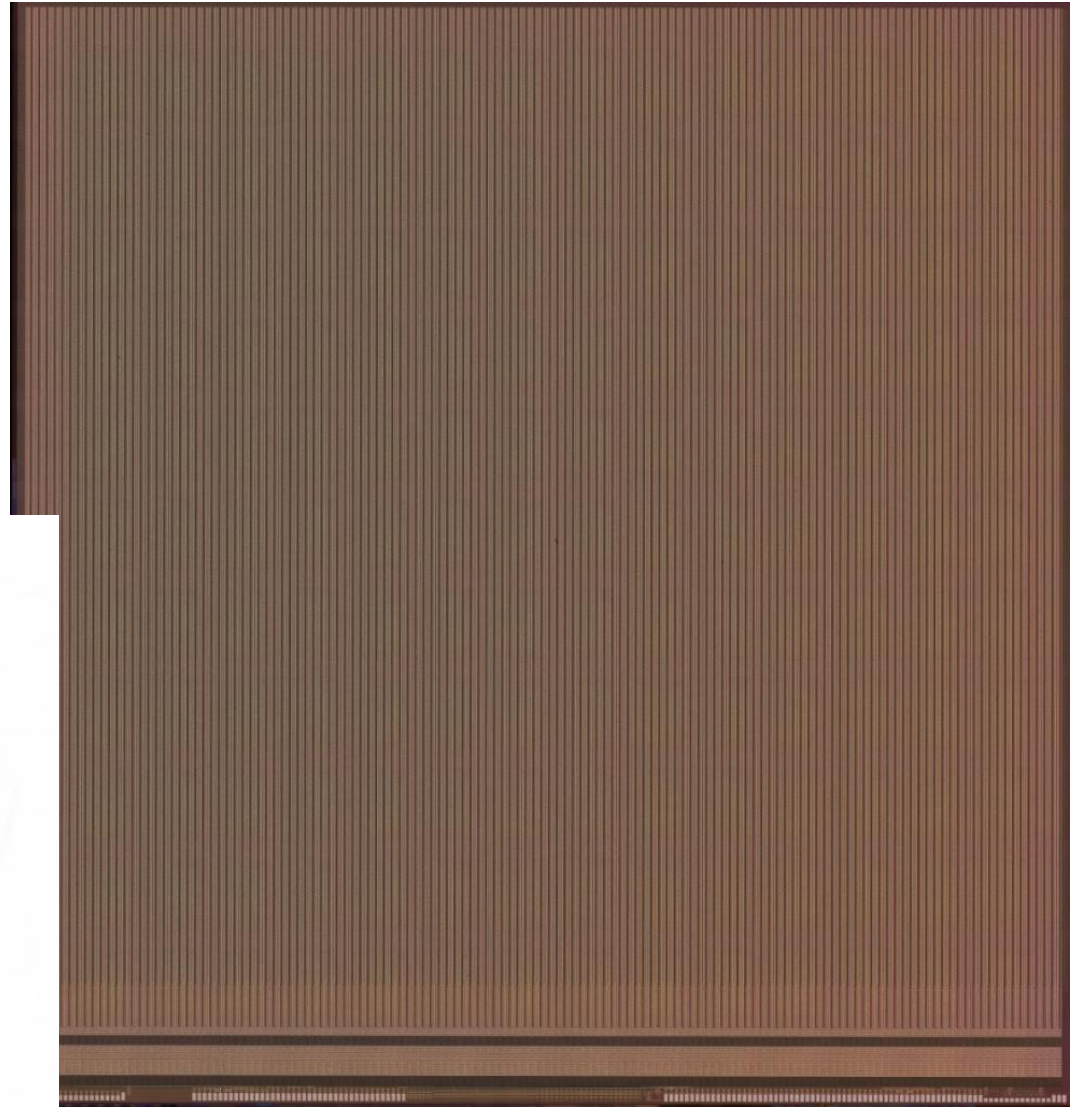


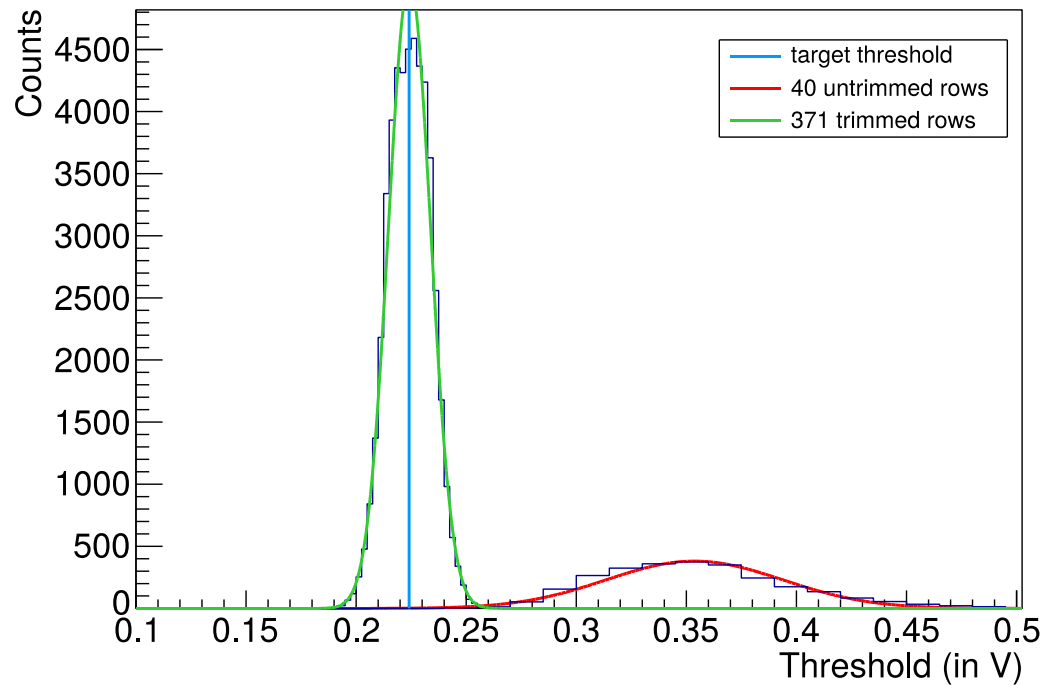




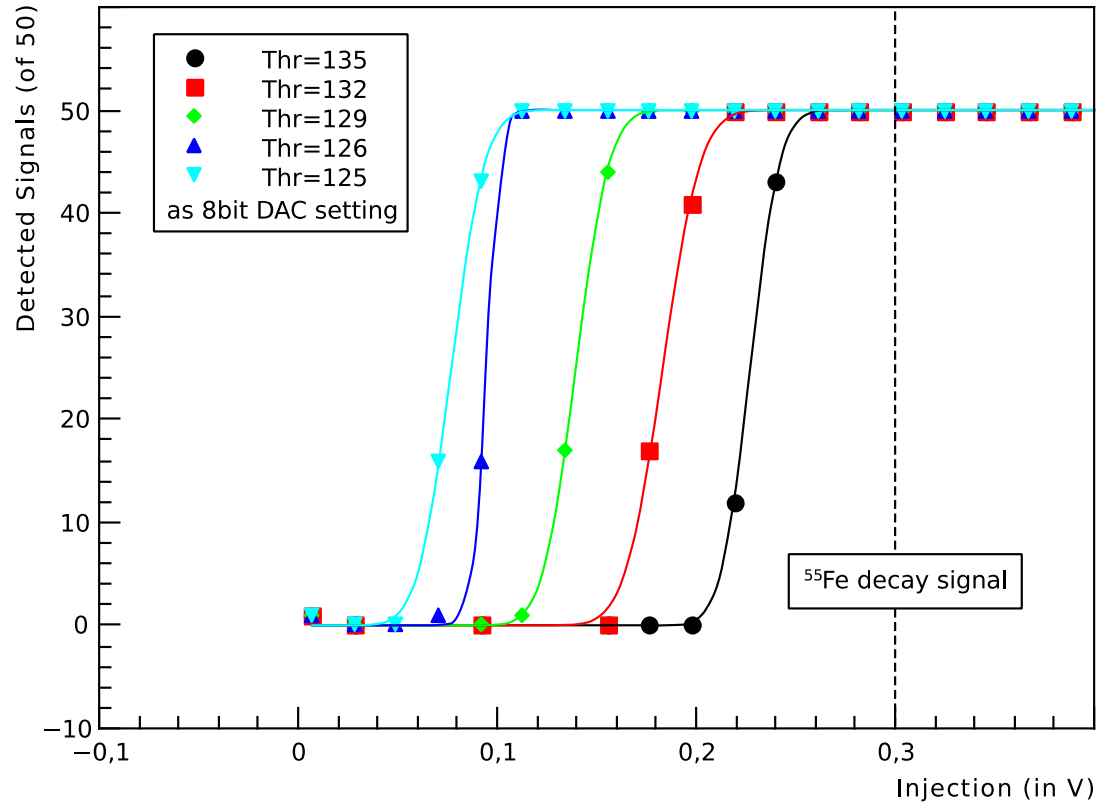




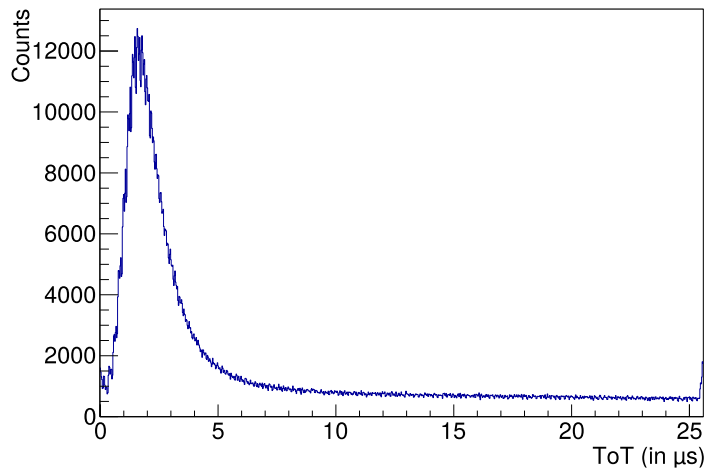




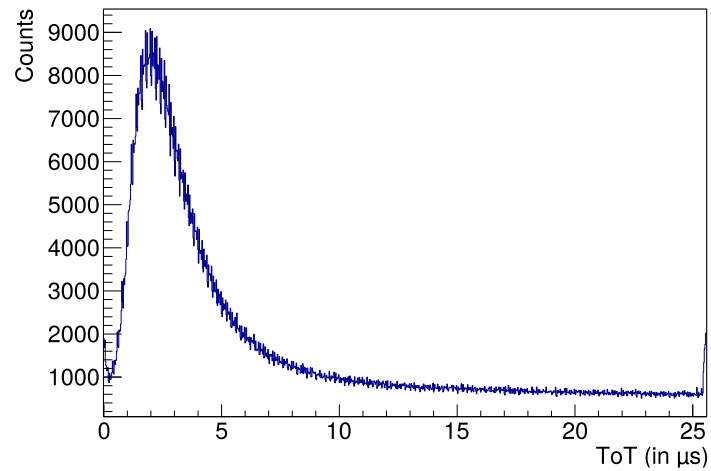
Sigma dispersion:  $52e^-$  (9.6mV) @  $1200e^-$  threshold (inj. Voltage 220mV)



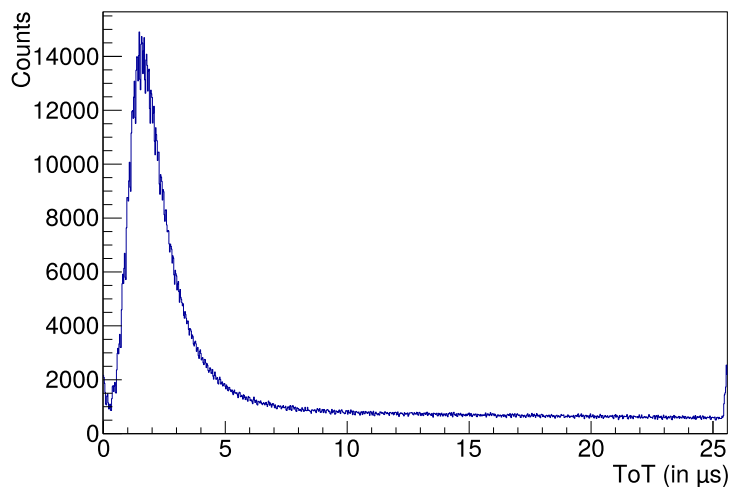
Layer 1



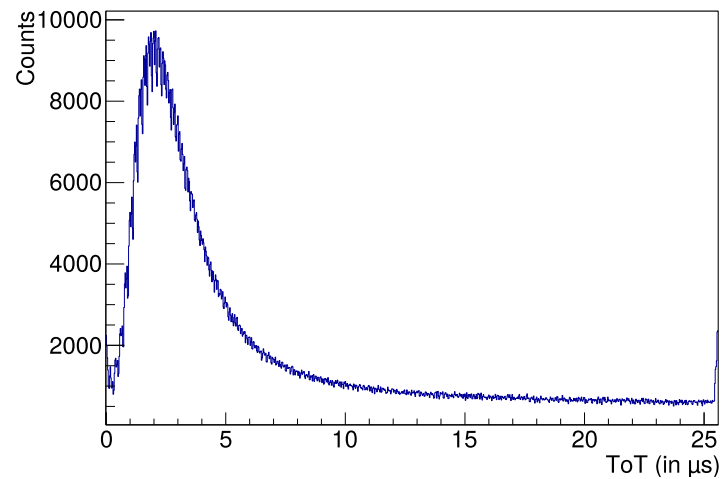
Layer 2



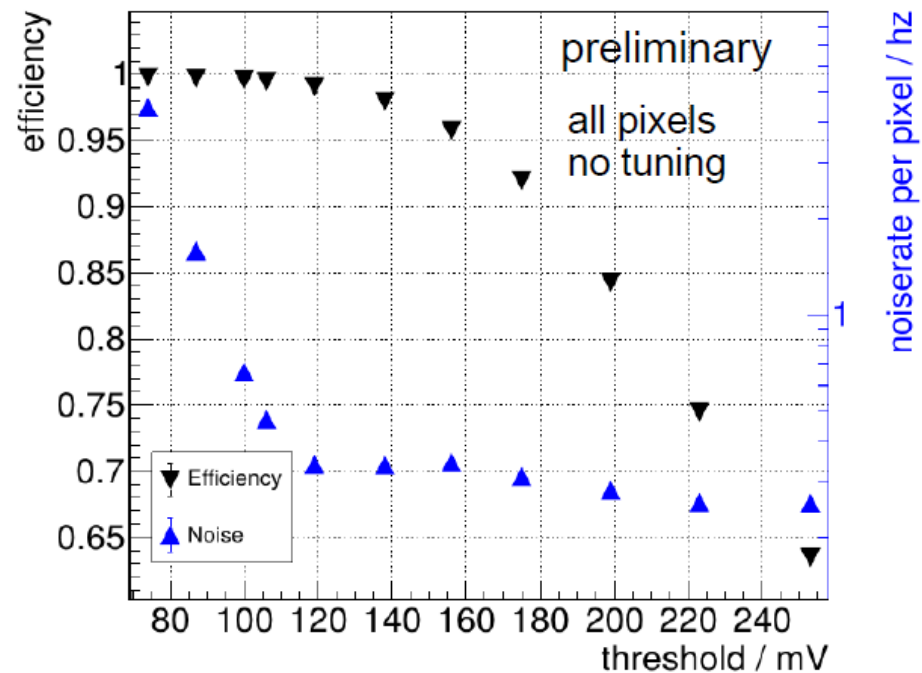
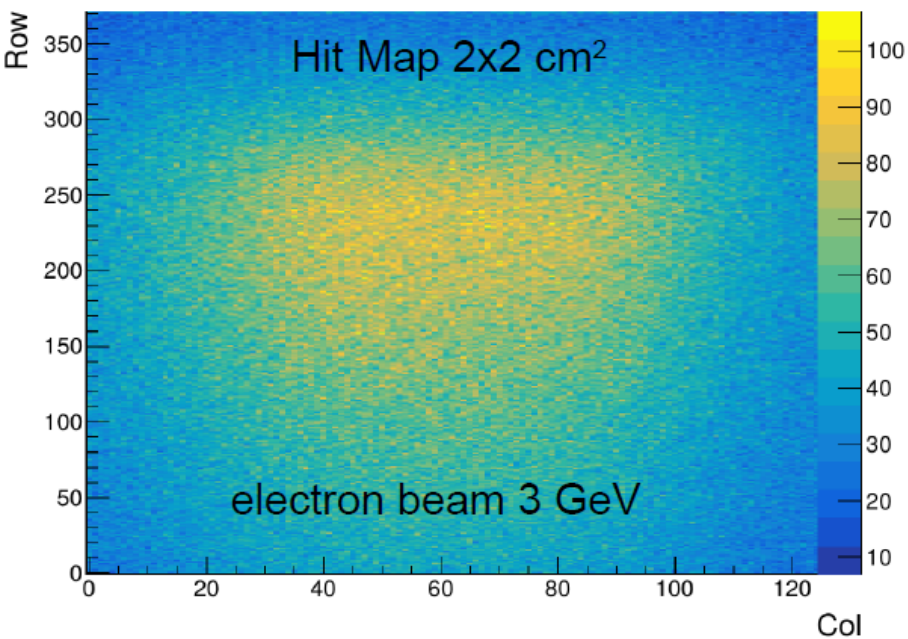
Layer 3



Layer 4



- Excellent efficiency



- ATLASPix3 is a full reticle, single matrix detector
- The detector is working and has a high yield
- Trimming is possible to compensate for threshold and timing differences
- A four layer beam telescope was developed and is operational
- Excellent efficiency in test beam

- MuPix10 is a full reticle, single matrix detector
- The chip design was submitted to TSI in December 2019, the wafers are ready to be shipped, tests will start in March 2020
- Advantage versus ATLASPIX3 – 3 data outputs, 3x higher data rate



- The chip has a size of **20.66×23.18mm** and contains **256 columns** each with **250 pixels**
- Each pixel has a size of **80 × 80 μm<sup>2</sup>**
- **The pixel electronics contains of a charge sensitive PMOS amplifier, its feedback and the output driver**
- The output driver of the pixel is connected to a long line to the readout buffer placed in the chip periphery
- The output of the pixels is a voltage signal, the output driver is realized with a source follower.
- The readout buffer contains different circuits for the following purposes: time measurement, amplitude measurement, address signal generation, temporary storage of the hit information (11 bit time stamp and 5 bit second time stamp for time over threshold calculation), priority ordered readout and hit bus signal generation.
- **There are two different modes of the readout buffer**
  - The two comparators are used with different threshold voltages. The output of the comparator with the smaller threshold is used for storing the timestamp. By this, the timewalk can be reduced. The hits are confirmed using the comparator with the higher threshold.
  - The other possibility is to turn one of the comparators off to allow a power saving modus and doing just a time over threshold (ToT) measurement.
- The threshold can be set for each comparators individually. The TDAC is extended so that every comparator has a 3-bit DAC and RAM cells
- **Matrix is divided into 3 segments**
- The RCU receives the signals of the corresponding matrix segment. The state machine generates the signals LdPix, Pull Down, LdCol and RdCol. RCU receives the hit data containing the two timestamps, the row address and the column address. **The output of the RCU are 3+1 parallel data words**
- Current mode DACs are 6-bit DACs made with current sources. These DACs produce currents. To bias a current source in a pixel, there is a diode connected transistor near the DAC. The DAC current generates voltage when it flows through the diode connected device. The voltage is distributed in the pixels and connected to the gates of the current sources.
- Voltage mode DAC uses a resistor ladder structure
- There are six independent shift registers. Bias, Config and VDAC are responsible for the global chip configuration. Col, TDAC and Test are responsible for the configuration of the chips test infrastructure (injection, ampout, hitbus), as well as the pixel tuning.

■ Thank you

- Triggered readout animation

